

Title (en)

HIGH-DENSITY WIRE BOND MICRODISPLAY

Title (de)

MIKROANZEIGE MIT DRAHTANSCHLÜSSEN HOHER DICHTHE

Title (fr)

MICROECRAN A HAUTE DENSITE DE CONNEXIONS PAR FILS

Publication

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Application

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Abstract (en)

[origin: WO0229480A2] A microdisplay system havng an improved packaging that is particularly useful in a high-density wire bonding system is herein provided. A frame structure helps support a flexible printed circuit having an extended portion. The extended permits standard-sized via placement using conventional drilling processes. The extended portion may be folded and creased out of the way and adhered to the underside of the display system. An increased number of traces is provided in a given area while maintaining the space and trace width requirements for cost effective manufacturing.

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IPC 8 full level

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